

What is claimed is:

1. A apparatus for discharging a waste gas in a semiconductor manufacturing process, comprising:
  - an inlet transfer 100 having an inlet port 102 disposed at its outer circumferential face and a support rib 104 disposed at its inner circumferential face;
  - a discharge transfer 140 having a support jaw 144 fixed to a support rib at its outer circumferential face, wherein the discharge transfer 140 is inserted into the inlet transfer 100 so that a blow-off gap 110 communicating with the inlet port is disposed between the bottom of the discharge transfer 140 and the inner circumferential face of the inlet transfer 100 and a high-pressure gas room 150 communicating with the inlet port and the blow-off gap is formed between the outer circumferential face of the discharge transfer 140 and the inner circumferential face of the inlet transfer 100;
  - a transfer cap 160 having the bottom coupled to the top of the inlet transfer, while surrounding the discharge transfer;
- 15 a heating casing 180 disposed around the inlet transfer and the transfer cap to form a heating room 182, and having a nitrogen inlet port 184 disposed on its outer circumferential face; an electric heat wire 200 disposed within the heating room; and a temperature sensor 220 for controlling a temperature of the electric heat wire.
- 20 2. The apparatus as claimed in claim 1, further comprising a burn preventing cap 240 surrounding a heating casing 180 with a given distance from the outer circumferential face of the heating casing.